

PRODUCT DATA SHEET

Indium8.9ES

Solder Paste

Introduction

Indium8.9ES is a no-clean solder paste for use in air or nitrogen reflow with tin-lead based solder alloys.

Indium8.9ES offers excellent print transfer efficiency to work in the broadest range of processes. In addition, the high oxidation resistance of **Indium8.9ES** virtually eliminates incomplete coalescence (graping) on small deposits.

Features

- Excellent printing performance
- Wide reflow window in both air and nitrogen and low peak reflow temperatures
- Strong wetting performance on a variety of surfaces
- Minimal voiding in QFN and BGA assemblies

Alloys

Indium Corporation manufactures low-oxide spherical powder in a wide variety of alloys. Type 3 and 4 powder are standard offerings with Sn62 and Sn63 alloys. The metal percent is the weight percent of the solder powder in the solder paste and is dependent upon the powder type and application.

Product Specifications

| Alloy | Powder Type | Metal Load |
|-----------|-------------|------------|
| Sn63/Pb37 | Type 4 | 90% |

Compatible Products

- **Rework Flux:** TACFlux®020B, TACFlux®089HF
- **Cored Wire:** CW-807
- **Wave Flux:** WF-7742, WF-9942

Bellcore and J-STD Tests and Results

| Test | Result | Test | Result |
|--|---------------|--|-------------|
| J-STD-004A (IPC-TM-650) | | J-STD-005 (IPC-TM-650) | |
| Flux Type (per J-STD-004A) | ROL1 | Typical Solder Paste Viscosity Malcom (10rpm) Sn63, 90%, Type 4 | 1,950 poise |
| Flux Induced Corrosion (Copper Mirror) | Type L | | |
| Presence of Halide Ion Chromatography | <0.5% Cl- eq. | Slump Test | Pass |
| SIR | Pass | Solder Ball Test | Pass |
| | | Typical Tackiness | 40g |
| | | Wetting Test | Pass |
| | | Electromigration | Pass |

All information is for reference only.
Not to be used as incoming product specifications.

Storage and Handling Procedures

Refrigerated storage will prolong the shelf life of solder paste. Solder paste packaged in cartridges should be stored tip down.

| Storage Conditions (unopened containers) | Shelf Life |
|--|------------|
| <10°C | 6 months |

Solder paste should be allowed to reach ambient working temperature prior to use. Generally, paste should be removed from refrigeration at least 2 hours before use. Actual time to reach thermal equilibrium will vary with container size. Paste temperature should be verified before use. Jars and cartridges should be labeled with date and time of opening.

Packaging

Indium8.9ES is currently available in 500g jars or 600g cartridges. Packaging for enclosed print head systems is also readily available. Alternate packaging options may be available upon request.

Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Material Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>



From One Engineer To Another®

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Printing

Stencil Design:

Electroformed and laser cut/electropolished stencils produce the best printing characteristics among stencil types. Stencil aperture design is a crucial step in optimizing the print process. The following are a few general recommendations:

- Discrete components—A 10–20% reduction of stencil aperture has significantly reduced or eliminated the occurrence of mid-chip solder beads. The “home plate” design is a common method for achieving this reduction.
- Fine-pitch components—A surface area reduction is recommended for apertures of 20mil pitch and finer. This reduction will help minimize solder balling and bridging that can lead to electrical shorts. The amount of reduction necessary is process-dependent (5–15% is common).
- For optimum transfer efficiency and release of the solder paste from the stencil apertures, industry standard aperture and aspect ratios should be adhered to.

| Printer Operation | |
|---------------------------|--|
| Solder Paste Bead Size | ~20–25mm in diameter |
| Print Speed | 25–125mm/second |
| Squeegee Pressure | 0.018–0.027kg/mm of blade length |
| Underside Stencil Wipe | Start at once per every 5 prints and decrease frequency until optimum value is reached |
| Squeegee Type/Angle | Metal with appropriate length / ~45 degrees |
| Separation Speed | 5–20mm/second or per equipment manufacturer's specifications |
| Solder Paste Stencil Life | >8 hours (at 30–60% RH and 22–28°C) |

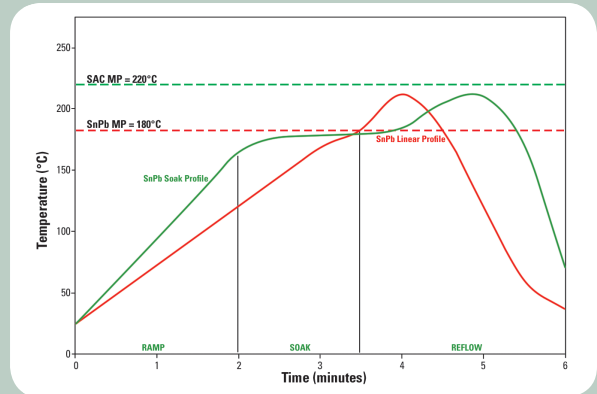
Cleaning

Indium8.9ES is designed for no-clean applications; however, the flux can be removed, if necessary, by using a commercially available flux residue remover.

Stencil cleaning is best performed using isopropyl alcohol (IPA) as a solvent. Most commercially available stencil cleaners work well.

Reflow

Recommended Profile:



This profile is designed for use with Sn63/Pb37 and Sn62/Pb36/Ag2 and can serve as a general guideline in establishing a reflow profile for use with other alloys. Adjustments to this profile may be necessary based on specific process requirements. Deviations from these recommendations are acceptable, and may be necessary, based on specific process requirements, including board size, thickness, and density. Start with the linear profile, then move to the optional soak profile, if needed. The flat soak portion of the linear profile (linear shoulder) may also be eliminated.

| Reflow Profile Details | SnPb Parameters | | Comments |
|---|-----------------------|------------------|--|
| | Recommended | Acceptable | |
| Ramp Profile (Average Ambient to Peak)— Not the Same as Maximum Rising Slope | 0.5–1°C/second | 0.5–2.5°C/second | To minimize solder balling, beading, hot slump |
| Soak Zone Profile (optional) | 30–90 seconds | 30–120 seconds | May minimize BGA/CSP voiding Eliminating/reducing the soak zone <u>may</u> help to reduce HIP and graping |
| | 140–150°C | 130–170°C | |
| Time Above Liquidus (TAL) | 45–60 seconds | 30–100 seconds | Needed for good wetting/reliable solder joint As measured with thermocouple |
| Peak Temperature | 198–213°C | 195–233°C | |
| Cooling Ramp Rate | 2–6°C/second | 0.5–6°C/second | Rapid cooling promotes fine-grain structure |
| Reflow Atmosphere | Air or N ₂ | | N ₂ preferred for small components |

All parameters are for reference only.
Modifications may be required to fit process and design.

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Contact our engineers today: askus@indium.com

Learn more: www.indium.com



ASIA +65 6268 8678 • CHINA +86 (0) 512 628 34900 • EUROPE +44 (0) 1908 580400 • USA +1 315 853 4900

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